



#25/Amdt F  
4/24/03  
c.p.

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q58486

Kouki OGAWA, et al.

Appln. No.: 09/538,469

Group Art Unit: 2814

Confirmation No.: 6688

Examiner: Nathan W. Ha

Filed: March 29, 2000

For: CAPACITOR-BUILT-IN TYPE PRINTED WIRING SUBSTRATE, PRINTED WIRING SUBSTRATE, AND CAPACITOR

RECEIVED  
APR 21 2003  
TECHNOLOGY CENTER 2800

AMENDMENT UNDER 37 C.F.R. § 1.111

Commissioner for Patents  
Washington, D.C. 20231

Sir:

This Amendment is submitted in response to the outstanding Office Action dated January 21, 2003. Please amend the above-identified application as follows.

IN THE CLAIMS:

Please enter the following amended claims:

F<sup>1</sup>

1. (Five times amended) A printed wiring substrate having a planar surface and a built-in capacitor having vertical sides on which an IC chip is mounted, said printed wiring substrate comprising a capacitor accommodation cavity selected from the group consisting of a closed-bottom cavity and a through hole cavity extending in the thickness direction of the printed wiring substrate and a capacitor disposed in said cavity, wherein the vertical sides of the capacitor and the printed wiring substrate are fixed together with an insulating resin filling a gap between the cavity and the capacitor, characterized in that:

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